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Revision:	Date:	Description:		Prepared:	Notes:					
Α	9/24/2018	Initial release			Function test: no open, no sho	rt circuit, no			VISII.	LITY
				Verified: Dimensions are in millimeters. Tolerances: < 1.0: ± 0.1 mm	intermittent s are in		tel 1.541.323.3228 800 877.670.7118 fax 1.541.323.4202 web tensility.com			
					llimeters. lerances: .0: ± 0.1 mm to 10.0: ± 0.2 mm Description: Connector, dc jack 5.5x2.5 mm, PCB mount, 90°, silver plated, thru hole		Size:	54.00400		
				1.0 to 10.0: ± 0.2 mr > 10.0: ± 0.3 mm			Scale:	4:1		Sheet 1 of 2
	•	5	2	1	3	2	•			1

Ratings

Maximum operating voltage: 48 V

Maximum operating current: 6.5 A (not mated under load)

Flammability: UL 94 V-0

Operating Temperature Range

-25 to 85 °C, relative humidity of 85% or less

Materials

1)Insulator: PBT, black

(2) Terminal: brass, silver plated

(3)Spring contact: phosphor bronze, silver plated

(4)Terminal: brass, silver plated

5)Center pin: copper alloy, nickel plated

6 Cover: brass, silver plated

Electrical Requirements

Dielectric strength: 1 min @ 500 Vac

Insulation resistance: 100 MΩ @ 500 Vdc minimum

Contact resistance: $50 \text{ m}\Omega$ maximum

Mechanical Requirements

Insertion force: 0.3-3.0 kgf

Withdrawal force: 0.3-3.0 kgf

Life cycle: 5000 mating cycles while maintaining contact resistance: 100 m Ω maximum, insulation resistance: 50 M Ω minimum, withstand voltage: 250 Vac, 1 min, and insertion/ extraction forces of 0.2-2.0 kgf

Terminal strength: 300 gf applied to the terminal for 15 seconds in any direction while maintaining electrical characteristics and without damage or excessive looseness of terminals

Soldering

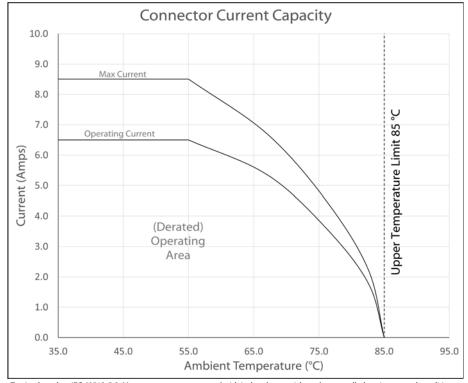
Solderability: 75% minimum coverage when terminals dipped 2mm in 245 \pm 5 °C solder bath for 3 \pm 0.5 seconds

Solder bath durability: no deformation when immersed in 255 ± 5 °C up to surface of the board 1.6 mm for 5 seconds or less

Solder iron durability: no deformation when exposed to 350 ± 10 °C for 3 ±0.5 seconds

Environmental Requirements

Cold test: -25 ± 3 °C for 48 hours without deformation Heat test: 85 ±2 °C, for 48 hours without deformation Humidity test: 40 ± 2 °C, relative humidity 90-95% for 48 hours without deformation



Testing based on IEC 60512-5-2. Max current curve generated with isolated test article under controlled environmental conditions, and does not take into account external factors such as housings, mating cables, or other circuitry. Operating current curve (derated by 20% of maximum values) accounts for external factors, and manufacturing variation.

Wave Soldering Temperature Profile

Pb - Free Flow Profile

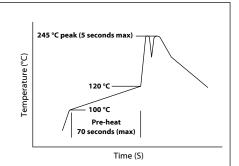
Solder temperature: 245 °C

Time: 5 seconds maximum

Pre-heat: 100 ~120°C

Time: 70 seconds maximum

Measure point: surface of the solder leads



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			Verified:	intermittent		te	1.541.	323.3228 800 8	377.670.7118	
			Dimensions are in	usions are in			fax 1.541.323.4202 web tensility.com			
			millimeters. Tolerances: < 1.0: ± 0.1 mm 1.0 to 10.0: ± 0.2 mm > 10.0: ± 0.3 mm	Description.			Size: Part number:			
				mm silver plated, thru hole	PCB mount, 90°,	А 54-00128				
						Scale:	5:1		Sheet 2 of 2	